

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0008] of the specification as originally filed with the amended paragraph below.

[0008] The tensile strength of the protective cap is preferably greater than about 30 GPa. The hardness of the protective cap is preferably greater than about 200 Brinell. The protective cap is preferably formed on an upper surface of the semiconductor device. Alternately, the protective cap may be formed on an upper surface of the semiconductor chip and between the semiconductor chip and the flexible substrate.

Please replace paragraph [0014] of the specification as originally filed with the amended paragraph below.

[0014] The tensile strength of the protective cap is preferably greater than about 30 GPa. The hardness of the protective cap is preferably greater than about 200 Brinell. The protective cap may be formed on an upper surface of the semiconductor chip or on an upper surface of the semiconductor chip and between the semiconductor chip and the flexible substrate.

Please replace paragraph [0035] of the specification as originally filed with the amended paragraph below.

[0035] In all of the foregoing manufacturing methods, the tensile strength of the protective cap or caps is preferably greater than about

30 GPa and the hardness of the protective cap or caps is preferably greater than about 200 Brinell. The flexible substrate is preferably formed of one selected from the group consisting of plastic and a thin metal film. Alternately, the flexible substrate may be a glass substrate having a thickness less than about 100 μm . The semiconductor chip is preferably one selected from the group consisting of a thin film transistor (TFT), a thin film diode (TFD), and a metal insulator metal (MIM). The driving unit may be a pixel unit of an LCD or a pixel unit of an OLED. The protective cap or caps is preferably formed of one selected from the group consisting of an ultraviolet curing resin, an X-ray curing material, an electronic beam curing material, and an ion beam curing material.

Please replace paragraph [0051] of the specification as originally filed with the amended paragraph below.

[0051] It is preferable that the protective cap 63 is formed of a material having a tensile strength higher than about 30 GPa and a hardness higher than about 200 Brinell. Examples of materials that may be used as the protective cap include an ultraviolet curing material, an X-ray curing material, an ion beam curing material, and an electronic beam curing material according to a curing method.